

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#1 1/2/A (3)
P. 6th
4-7-03

In re PATENT APPLICATION of

Hiroyuki Nishi et al.

Attn: Applications Branch

Divisional of Serial No.: 09/265,841

Attorney Docket No. SKI.007D

Filed: June 29, 2001

For: TRANSFER MOLDING APPARATUS AND METHOD FOR MANUFACTURING
SEMICONDUCTOR DEVICES

PRELIMINARY AMENDMENT

Honorable Assistant Commissioner for Patents
Washington, D.C. 20231

Date: June 29, 2001

Sir:

Preliminary to the examination of the above-identified application, please enter
the following amendments and remarks.

In the Abstract:

Please cancel the Abstract and replace with the Abstract attached herewith.

In the Specification:

Kindly amend the specification as follows:

Page 1, between lines 3 and 4, insert

--CROSS REFERENCE TO RELATED APPLICATIONS

This is a divisional application of application Serial No. 09/265,841, filed March
10, 1999, which is hereby incorporated by reference in its entirety for all purposes.--

FORWARDED - 06/29/01

OK
ENTER
8/1/01
A 1 Sub B2